

# Green World Technologies Corporation

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## RoHS COMPLIANCE STATEMENT

### 1. SCOPE

This statement clarifies Green World Technologies corporation's product compliance with the European Union's directive 2002/95/EC, Restrictions of Hazardous Substances ("RoHS" directive) and similar regulations that may be adopted by other countries.

RoHS directive becomes valid on Jul 1 2006 in the member states of European Union. It states that all new electrical and electronic equipment put on the market within the member states must not contain certain hazardous materials.

### 2. RESTRICTED (RoHS) MATERIALS

Quantity limit 0.1% of weight (1000ppm) of any homogeneous material:

1. Lead (Pb)
2. Mercury (Hg)
3. Hexavalent Chromium (Cr VI)
4. Flame retardants Polybrominated Biphenyls (PBB) and Polybrominated Diphenyl Ethers (PBDE)

Quantity limit 0.01% of weight (100 ppm) of any homogeneous material: Cadmium (Cd)

'Homogeneous material' means a material that cannot be mechanically disjointed into different materials by, for example unscrewing, cutting, crushing, grinding and abrasive processes.

Homogeneous is further defined as "of uniform composition throughout".

### 3. EXEMPTIONS

Following cases are exempted from the requirements:

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
2. Mercury in straight fluorescent lamps for general purposes not exceeding:
  - halo phosphate 10 mg
  - triphosphate with normal lifetime 5 mg
  - triphosphate with long lifetime 8 mg.
3. Mercury in straight fluorescent lamps for special purposes.
4. Mercury in other lamps not specifically mentioned in this Annex.
5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6. Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminum containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
7. Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85 % lead), lead in solders for servers, storage and storage array systems (exemption granted until 2010), lead in solders for network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunication, lead in electronic ceramic parts (e.g. piezo-electronic devices).